

### **AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph [030] with the following amended paragraph:

[030] The process of manufacturing the lead frame connector includes a step of stamping the appropriate conductor structure and configuration in a ribbon of conductive material. For example, the general conductor configuration 34 shown in Figures 2b and 3b can be formed by stamping a copper ribbon, shown at 60 in Figures 5A and 5B, which figures depict two possible ribbon configurations. The conductor configuration can be easily selected to conform with the conductor design that has been determined to have acceptable electrical performance as described above.

Please replace paragraph [031] with the following amended paragraph:

[031] The stamped ribbon is spooled from one reel 62 to another reel 64, as shown in Figure 6, while being passed through the insert injection molding process. During this process, the conductors 34 of the stamped ribbon 60 are bent or manipulated as needed in three dimensions as shown, for example, in Figures 2b and 3b, to achieve the necessary three-dimensional conductor configuration. The insert injection molding process by injection mold 66 forms the plastic casing about the lead frame, which provides mechanical support and electrical isolation for the conductors.

Please replace paragraph [032] with the following amended paragraph:

[032] After the plastic casing 32 is formed, the lead frame assembly is passed through a singulation die 68 that dices the ribbon into individual lead frame assemblies. During the preceding insert injection molding process, the individual conductors in the lead frame are held together using a portion of the lead frame. In general, lead frame manufacturing processes use a

portion of the lead frame structure to mechanically stabilize the individual conductors during the stamping and molding process. Conventional lead frame manufacturing processes typically use external stabilization, meaning that the individual conductors are typically stabilized and connected to an external support structure that is sheared off during the singulation stage. One problem associated with stabilization and singulation in this manner is that conductive stubs often remain in electrical contact with the leads after this step. Sizeable stubs can act as antennas and degrade the RF response of the lead frame structure.